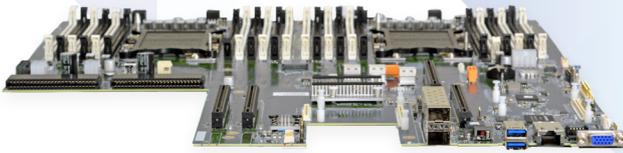


Inventec® at core

One Advanced Board for Wide Applications



B888G4 - L-shape High Density Motherboard

B888G4 motherboard targets general purpose usage for enterprises and datacenters with dual Intel® Xeon® Scalable Processors, twenty-four DIMM capacity (up to 3TB with 128GB DIMMs) and four PCIe expansion slots. Offering better flexibility, higher performance and greater memory density, B888G4 is made applicable for a wide variety of virtualization solutions, big data analysis scenarios, among others. The series presents,

Highlights -

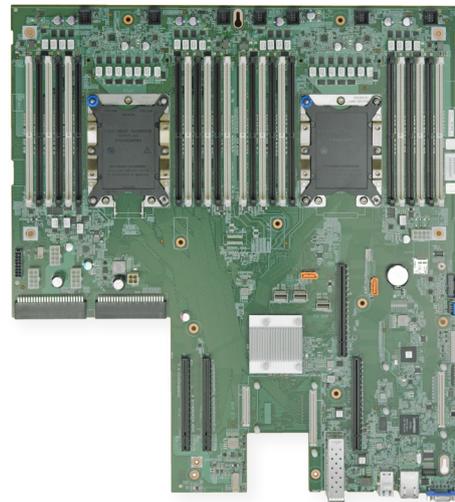
- Non-shadow L-shape MLB with dual Intel® Xeon® Scalable Processors, supporting onboard 10GbE Network
- High Density Memory, up to 24 DDR4 DIMM slots
- Flexible I/O Design with Great Scalability

High Performance

The new generation Intel® Xeon® Processor Scalable Family are based on Intel 14nm process technology that lay new foundation of scalability offering optimized workload for synergy across compute, network and storage, with up to 3.9x higher virtualized workload throughput and number of VMs, a great boost in performance, security, agility and efficiency, catering to wide range of key workloads.

Great Density and Scalability

Adopting Intel® C622 chipset, supporting dual Intel® Xeon® Processor Scalable Family and up to 3TB of DDR4 memory. B888G4 motherboard hosts four PCIe x16 lanes, enabling expansion of up to six PCIe cards with riser boards, and support the latest Intel® technologies, such as Intel® Optane™ Persistent Memory which is ready with platform codenamed Cascade Lake, etc.



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PCI EXPRESS

DDR-4

Flexible Network Configuration

Offering dual 10G SFP+ onboard NIC (Network Interface Controller), and supporting a variety of network choices through the OCP NIC mezzanine slot, ranging from 10G Ethernet to 100G (optical or Base-T, compatible with OCP 2.0), the high-speed performance and IO flexibility are realized by B888G4, catering to suitable demands of different application procedures. ▶

Model Name	B888G4
Positioning	General Purpose
Applied System Model	K888G4 (2U Mainstream Server) P90G4 (4U 8PGPU AI Server)
Form Factor	L-Shape, non-shadow W x L: 471.12 x 431mm (18.55" x 16.97")
Processor	Dual Socket (LGA-3647) Intel® Xeon® Processor Scalable Family TDP: up to 205W System Bus: up to 10.4 GT/s by Intel® UPI
Memory Slot	24x DDR4 DIMM slot 6 channels per socket with 2 DPC DIMM Type: ECC RDIMM, LRDIMM, at 1866/2133/2400/2666MHz Supporting Intel® Optane™ Persistent Memory
Chipset	Intel® C620 series (C622) Supporting 10GbE network
Expansion Slot	4x PCIe Gen3 x16 1x PCIe Gen3 OCP 2.0 A+B NIC mezz 1x Inventec Storage mezz
Network Controller	Onboard: Dual 10G SFP+ Supporting 25GE / 50GbE / 100GbE Mezz card
Storage Controller	Onboard: 2x SATA connector, 3x miniSAS HD connector; Up to 14x SATA3 6Gb/s port Intel RST RAID 0/1/5/10 Supporting Inventec Storage HBA/RAID Card
System Management	IPMI 2.0 compliant+ KVM with Dedicated LAN
BMC	AST2500 Shared NIC Management feature
TPM	Option: 2.0

ABOUT INVENTEC

Inventec Enterprise Business Group (EBG) was established in 1998 and has been focusing on the design and manufacturing of server systems. Inventec EBG is the key server system supplier of the global branding clients.

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